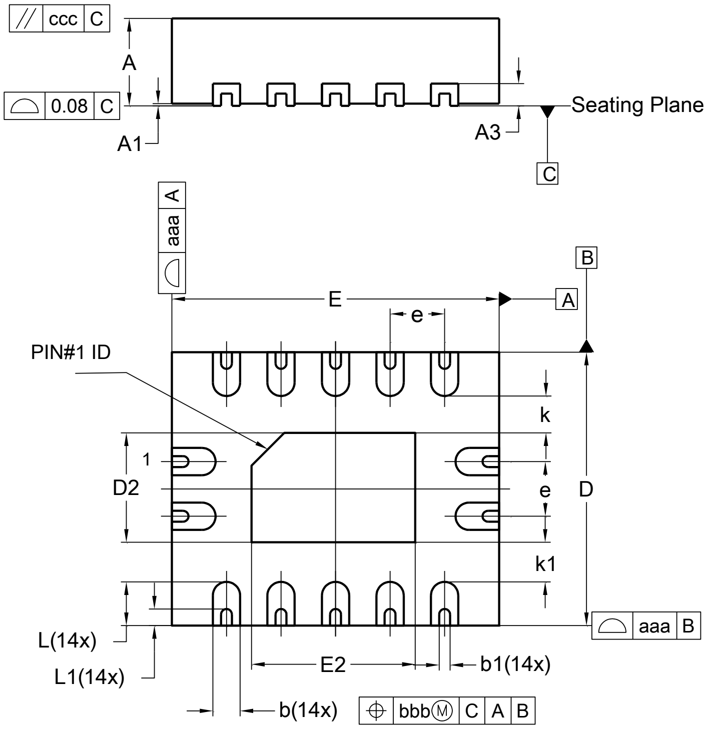
Package Outline Dimensions

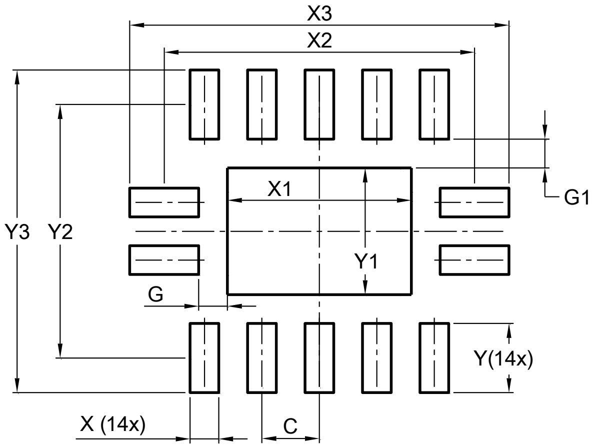
V-QFN2530-14/SWP (Type B)



V-QFN2530-14/SWP (Type B)			
Dim	**Min**	**Max**	**Typ**
A	0.75	0.85	0.80
A1	0.00	0.05	0.03
A3	--	--	0.203
b	0.20	0.30	0.25
b1	0.10	0.20	0.15
D	2.45	2.55	2.50
D2	0.90	1.10	1.00
E	2.95	3.05	3.00
E2	1.40	1.60	1.50
e	0.50 BSC		
k	--	--	0.338
k1	--	--	0.362
L	0.35	0.45	0.40
L1	0.15 REF		
aaa	0.250		
bbb	0.100		
ccc	0.100		
All Dimensions in mm			

Suggested Pad Layout

V-QFN2530-14/SWP (Type B)



Dimensions	Value (in mm)
C	0.500
G	0.250
G1	0.250
X	0.250
X1	1.600
X2	2.700
X3	3.300
Y	0.600
Y1	1.100
Y2	2.200
Y3	2.800

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.